May 2001

FDS9953A Dual 30V P-Channel PowerTrench[®] MOSFET

General Description

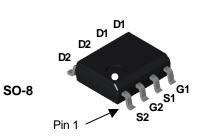
This P.Channel MOSFET is a rugged gate version of Fairchild Semiconductor's advanced PowerTrench process. It has been optimized for power management applications requiring a wide range of gave drive voltage ratings (4.5V - 25V).

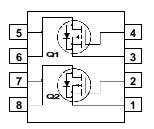
Applications

- Power management
- Load switch
- Battery protection

Features

- -2.9 A, -30 V $R_{DS(ON)} = 130 \text{ m}\Omega @ V_{GS} = -10 \text{ V}$ $R_{DS(ON)} = 200 \text{ m}\Omega @ V_{GS} = -4.5 \text{ V}$
- Low gate charge (2.5nC typical)
- Fast switching speed
- + High performance trench technology for extremely low $R_{\text{DS}(\text{ON})}$
- High power and current handling capability





Absolute Maximum Ratings T_A=25°C unless otherwise noted

| Symbol | Parameter | | | Ratings | Units |
|-----------------------------------|--|---|---------------|-------------|------------|
| V _{DSS} | Drain-Source | Voltage | -30 | V | |
| V _{GSS} | Gate-Source Voltage | | | ±25 | |
| l _D | Drain Current | t – Continuous | (Note 1a) | ±2.9 | Α |
| | | – Pulsed | | ±10 | |
| P₀ | Power Dissipation for Dual Operation | | | 2 | W |
| | Power Dissipation for Single Operation | | (Note 1a) | 1.6 | |
| | | | (Note 1b) | 1 | |
| | | | (Note 1c) | 0.9 | |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | | erature Range | -55 to +150 | |
| Therma | I Characte | eristics | | | |
| $R_{\theta JA}$ | Thermal Res | Thermal Resistance, Junction-to-Ambient (Note 1a) | | 78 | |
| R _{0JC} | Thermal Resistance, Junction-to-Case (Note 1) | | (Note 1) | 40 ° | |
| Packag | e Marking | and Ordering In | formation | | · · · · |
| Device Marking | | Device | Reel Size | Tape width | Quantity |
| FDS9953A | | FDS9953A | 13" | 12mm | 2500 units |

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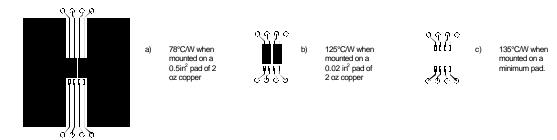
FDS9953A

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|--------------------------------------|---|---|------|-------------------------|--------------------------|-------|
| Off Char | acteristics | | | | | |
| BV _{DSS} | Drain–Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$ | -30 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | I_D = -250 μ A, Referenced to 25°C | | -23 | | mV/°C |
| | Zero Gate Voltage Drain Current | $V_{\text{DS}} = -24 \text{ V}, \qquad V_{\text{GS}} = 0 \text{ V}$ | | | -2 | μA |
| GSSF | Gate-Body Leakage, Forward | $V_{GS} = -25 \text{ V}, \qquad V_{DS} = 0 \text{ V}$ | | | -100 | nA |
| GSSR | Gate-Body Leakage, Reverse | $V_{GS} = 25 \text{ V}, \qquad V_{DS} = 0 \text{ V}$ | | | 100 | nA |
| On Char | acteristics (Note 2) | | I | | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = -250 \ \mu A$ | -1 | -1.8 | -3.0 | V |
| $\Delta V_{GS(th)} \Delta T_J$ | Gate Threshold Voltage Temperature Coefficient | $l_D = -250 \ \mu\text{A}$, Referenced to 25°C | | 4 | | mV/°C |
| R _{DS(on)} | Static Drain–Source On–Resistance | | | 95 137 142 202 | 130 200 200 310 | mΩ |
| | On–State Drain Current | | -5 | | | Α |
| D(on) | | $V_{GS} = -4.5 \text{ V}, V_{DS} = -5 \text{ V}$ | -1.5 | | | |
| g fs | Forward Transconductance | $V_{DS} = -15 V$, $I_D = -1 A$ | | 4 | | S |
| Dynamic | Characteristics | | | | | |
| C _{iss} | Input Capacitance | $V_{DS} = -15 V$, $V_{GS} = 0 V$, | | 185 | | pF |
| Coss | Output Capacitance | | | 56 | | pF |
| C _{rss} | Reverse Transfer Capacitance | f = 1.0 MHz | | 26 | | pF |
| Switchin | g Characteristics (Note 2) | | | | | |
| t _{d(on)} | Turn–On Delay Time | $V_{DD} = -15 V$, $I_D = -1 A$, | | 4.5 | 9 | ns |
| t _r | Turn–On Rise Time | $V_{GS} = -10 \text{ V}, \qquad R_{GEN} = 6 \ \Omega$ | | 13 | 23 | ns |
| t _{d(off)} | Turn–Off Delay Time | | | 11 | 20 | ns |
| t _f | Turn–Off Fall Time | | | 2 | 4 | ns |
| Qg | Total Gate Charge | $V_{DS} = -5 V$, $I_D = -1 A$, | | 2.5 | 3.5 | nC |
| Q _{gs} | Gate-Source Charge | $V_{GS} = -10 V$ | | 0.8 | | nC |
| Q _{gd} | Gate-Drain Charge | | | 0.9 | | nC |
| Drain-So | ource Diode Characteristics | and Maximum Ratings | | | | |
| ls | Maximum Continuous Drain-Source | - | | | -1.2 | Α |
| V _{SD} | Drain–Source Diode Forward Voltage | $V_{GS} = 0 V, I_S = -1.3 A$ (Note 2) | | -0.8 | 1.3 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0 V, l⊧ = −1.25A, dl⊧/dt = 100A/µs | | 17 | 100 | nS |

Typical Characteristics

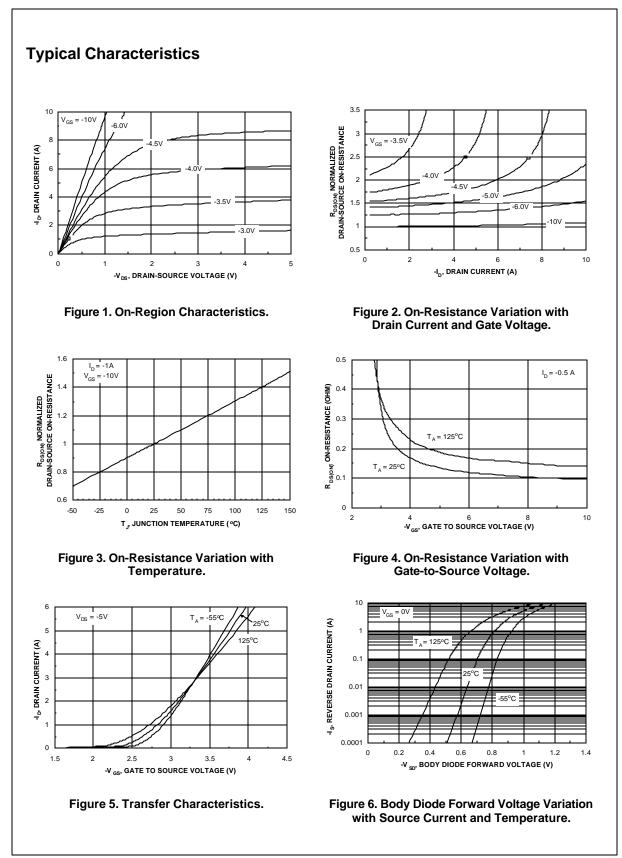
Notes:

 R_{RUR} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{RUC} is guaranteed by design while R_{RCA} is determined by the user's board design.

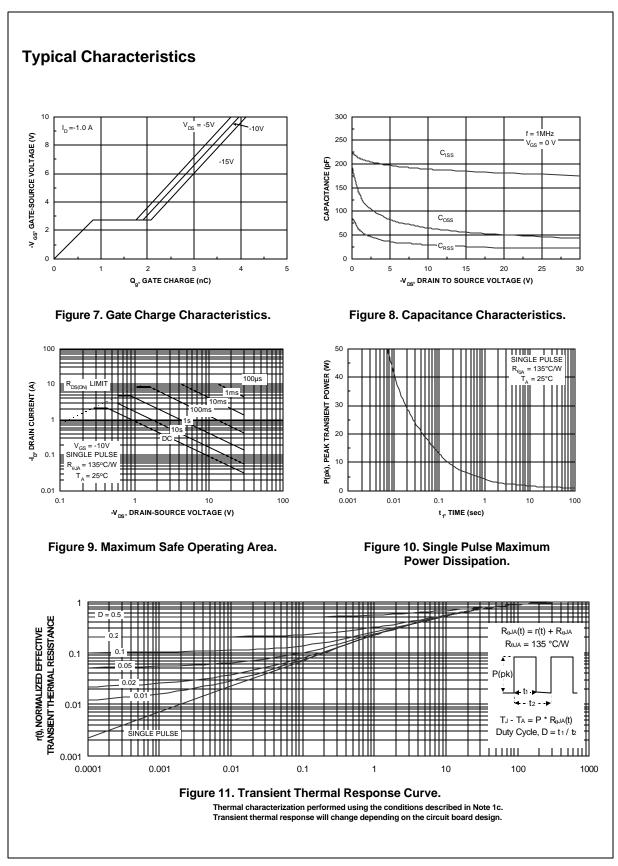


Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%



FDS9953A



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